



Material Content Data Sheet



Sales Product Name		XMC1302-T038X0200 AA		Issued		14. September 2015		
MA#		MA001406974						
Package		PG-TSSOP-38-9		Weight*		118.36 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.097	0.93	0.93	9272	9272
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	zinc	7440-66-6	0.060	0.05		506	
	non noble metal	iron	7439-89-6	1.199	1.01		10129	
wire	non noble metal	copper	7440-50-8	48.679	41.13	42.20	411298	422060
	noble metal	palladium	7440-05-3	0.003	0.00		26	
encapsulation	non noble metal	copper	7440-50-8	0.308	0.26	0.26	2599	2625
	organic material	carbon black	1333-86-4	0.192	0.16		1623	
	plastics	epoxy resin	-	7.494	6.33		63314	
leadfinish	inorganic material	silicondioxide	60676-86-0	56.362	47.63	54.12	476206	541143
	non noble metal	tin	7440-31-5	2.200	1.86	1.86	18586	18586
plating	noble metal	silver	7440-22-4	0.337	0.28	0.28	2850	2850
glue	plastics	epoxy resin	-	0.102	0.09		866	
	noble metal	silver	7440-22-4	0.307	0.26	0.35	2598	3464
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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